

# SPECIALTY PCB



## CAPABILITIES

### METAL SUBSTRATE PCB

Aluminum Substrate, Copper Subs Aluminum Substrate and Copper Substrates	
Metal-Substrate Control Depth Capability (mm)	±0.05
Counter Bore Depth-Controlled Capability (mm)	±0.10
Maximum Copper Weight (OZ)	12

### SPECIAL PROCESSES

Heat Sink	Embedded Resistance
ViPPO	Embedded Capacitance
Resin Fill	Hybrid Lamination
[Conductive and Non-Conductive]	Micro-Via Copper Fill
Oversize Backplane	Heavy Copper UL - 60oz
Metal-Buried PCB	Back Drill

### SURFACE FINISHES

- HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

### MATERIALS

- Standard Tg FR-4
- Mid Tg FR-4
- High Tg FR-4
- Polyimide
- High Speed Materials
- Mixed Dielectric Constructions

### CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

### LEAD TIMES

Lead times vary widely depending on material selection and technology level. Lead time can be evaluated at time of quote.



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Production Base

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